DATA SHEET

PCF8522E

256 × 8-bit CMOS EEPROM with I²C-bus interface

Objective specification

File under Integrated Circuits, IC12

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Philips Semiconductors

PHILIPS

256 × 8-bit CMOS EEPROM with I²C-bus interface

PCF8522E

CONTENTS

256 × 8-bit CMOS EEPROM with I²C-bus interface

PCF8522E

1 FEATURES

- Low power CMOS:
  - operating current: <2 mA
  - standby current: <2 μA
- Hardware write protection:
  - Write Control (WC) pin
- Operation supply voltage 2.7 to 5.5 V
- Extended temperature range –40 to +85 °C
- Internally organized as 256 × 8-bit memory bank
- I²C interface (bidirectional data transfer protocol)
- Four-byte page-write mode (minimizes total write time per byte
- Automatic word address incrementing (sequential register read)
- Self-timed write cycle
- High reliability:
  - endurance: 100000 cycles per byte
  - data retention: 10 years
- DIP8 or SO8 package (8 pins).

2 APPLICATIONS

The PCF8522E is ideal for high-volume applications requiring low power and low density storage.

Typical applications:

- Televisions
- Monitors
- Robotics
- Alarm devices
- Electronic locks
- Measuring devices
- Instrumentation.

3 GENERAL DESCRIPTION

The PCF8522E is a cost effective 2048 bit (256 × 8-bit) serial Electrical Erasable Programmable Read Only Memory (EEPROM). The device is fabricated using advanced CMOS EEPROM technology. This IC operates from a single supply voltage within the range of 2.7 to 5.5 V.

The PCF8522E is internally organized as a 256 × 8-bit memory bank. It features an I²C-bus serial interface and software protocol allowing operation on a 2-wire bus.

Up to eight PCF8522Es may be connected to the 2-wire bus establishing their device addresses using the address input pins (A0 to A2).

4 ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PCF8522EP	DIP8	plastic dual in-line package; 8 leads (300 mil)	SOT97-1
PCF8522ET	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1

5 BLOCK DIAGRAM

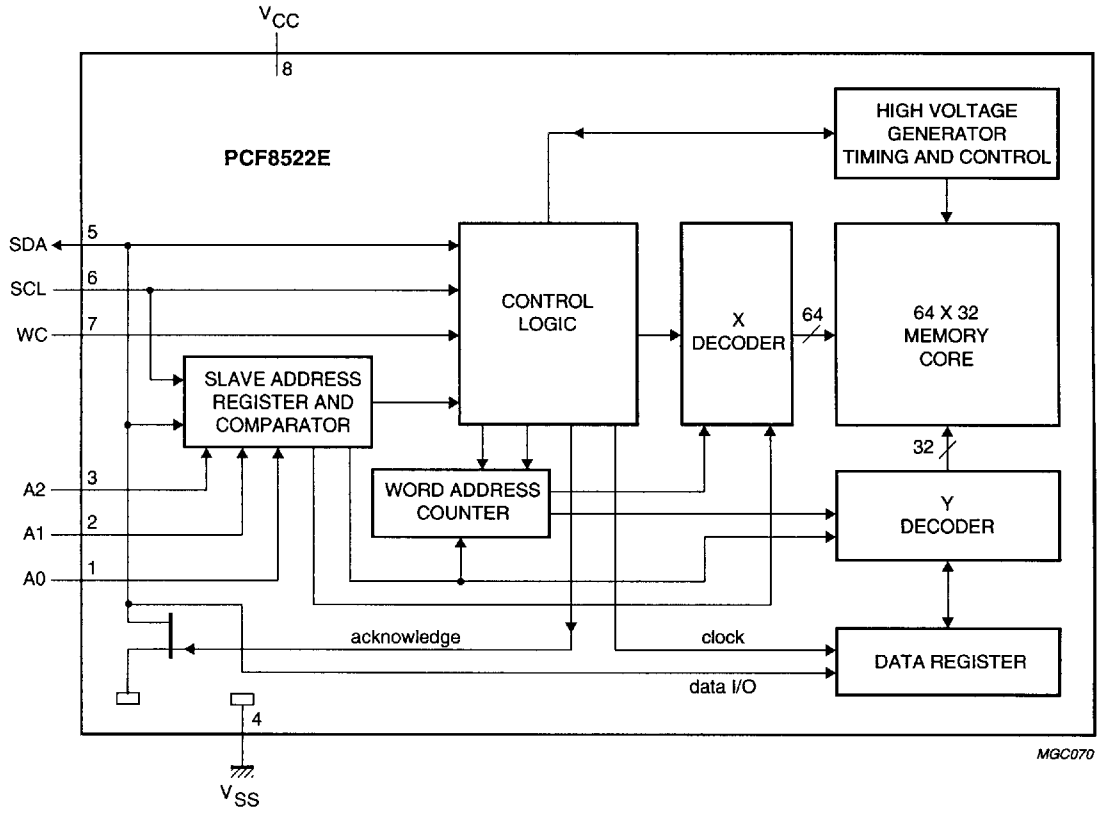


Fig.1 Block diagram.

6 PINNING

SYMBOL	PIN	DESCRIPTION
A0	1	address 1 input
A1	2	address 2 input
A2	3	address 3 input
V_{SS}	4	ground
SDA	5	serial data input/output (I/O)
SCL	6	serial clock input
WC	7	write control input
V_{CC}	8	supply voltage

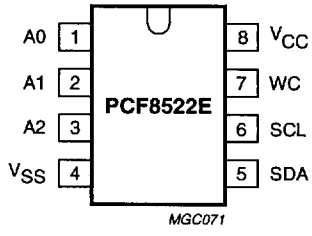


Fig.2 Pin configuration.

7 FUNCTIONAL DESCRIPTION

7.1 Pinning information

7.1.1 SERIAL CLOCK (SCL)

The SCL input is used to clock data into and out of the device. In the write mode, data must remain stable when SCL is HIGH. In the read mode, data is clocked out on the falling edge of SCL.

7.1.2 SERIAL DATA (SDA)

The SDA pin is a bidirectional pin used to transfer data into and out of the device. Data may only change when SCL is LOW, except START and STOP conditions. It is an open-drain output, and may be wire-ORed with any number of open-drain or open-collector outputs.

7.1.3 ADDRESS PINS (A0 TO A2)

The address inputs are used to set the 3-bit device address of the PCF8522E which will identify it on the I²C-bus. The address pins may be tied HIGH or LOW, or they may be actively driven. These inputs allow up to eight PCF8522E devices to be distinguished on the I²C-bus.

7.1.4 WRITE CONTROL (WC)

The write control input pin is used to disable the write circuitry to the memory. If WC = HIGH the write function is disabled, to protect previously written data. If WC = LOW the write function is enabled.

7.2 Endurance and data retention

The PCF8522E is designed for applications requiring up to 100000 write cycles and unlimited number of read cycles. It provides 10 years of secure data retention, with or without supply voltage applied, after the execution of 100000 write cycles.

7.3 Characteristics of the I²C-bus

7.3.1 GENERAL DESCRIPTION

The I²C-bus is designed for two-way, 2-line serial communication for different integrated circuits. The 2-lines are:

1. Serial Data line (SDA).
2. Serial Clock Line (SCL).

The SDA line must be connected to the positive supply voltage by a pull-up resistor, located somewhere on the I²C-bus (see Fig.3)). Data transfer between devices may be initiated with a START condition only when SCL and SDA are HIGH (I²C-bus is not busy).

7.3.2 INPUT DATA PROTOCOL

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable while the clock is HIGH, because changes on the data line, while SCL is HIGH will be interpreted as a 'START' or 'STOP' condition (see Fig.4).

7.3.3 START AND STOP CONDITIONS.

When both data (SDA) and clock (SCL) lines are HIGH, the I²C-bus is referred to as 'not busy'. A HIGH-to-LOW transition of the data line, while the clock is HIGH is defined as the 'START' condition. A LOW-to-HIGH transition of the data line, while the clock is HIGH, is defined as the 'STOP' condition (see Fig.5).

7.4 Device operation

The device supports the I²C-bus bidirectional data transmission protocol. The protocol defines any device that sends data onto the I²C-bus as a 'transmitter' and the receiving device as the 'receiver'. The device controlling the data transmission is the 'master' and the controlled device is the 'slave'. In all events the PCF8522E will be a 'slave' device because it never initiates any data transfers.

Up to eight PCF8522Es can be connected to the I²C-bus and can be selected by the A0 to A2 device addresses. A0 to A2 must be connected to either V_{CC}, V_{SS} or they may be actively driven. A0 to A2 define the address of the device. Other devices may be connected to the I²C-bus but each device needs its own device identification code.

7.4.1 Acknowledge (ACK)

Acknowledge is a software convention used to indicate successful data transfers. The transmitting device, either the master or the slave, will release the I²C-bus after transmitting 8-bits. During the ninth clock cycle, the receiver will pull the SDA line LOW to acknowledge that it has received 8-bits of data (see Fig.6).

The PCF8522E will respond with an acknowledge after recognition of a START condition and its slave address byte. If both the device and a write operation have been selected, the PCF8522E will respond with an acknowledge after the receipt of each subsequent 8-bit word.

In the read mode, the PCF8522E transmits 8-bits of data, then releases the SDA line, and monitors the line for an acknowledge signal. If an acknowledge is detected, and no STOP condition is generated by the master, the PCF8522E will continue to transmit data.

If an acknowledge is not detected, the PCF8522E terminates further data transmissions and awaits a STOP condition before returning to the standby power mode.

7.4.2 Slave address byte

Following a START condition, the master must output the address to be accessed. The most significant 4 bits of the slave address are the 'device type identifier'. For a PCF8522E the address identifier is 1010 (see Table 1).

The next 3 bits are device address, addressing a particular device. Using this addressing scheme, a system may cascade up to eight PCF8522E devices on the I²C-bus. The device address is defined by the state of the A0 to A2 input pins.

7.4.3 Read/write bit

The last bit of the slave address defines the operation to be performed. When R/$\overline{W}$ = 1, a read operation is selected. If R/$\overline{W}$ = 0, a write operation is selected (see Table 1).

Table 1 Slave address byte

DEVICE TYPE IDENTIFIER				DEVICE ADDRESS			R/$\overline{W}$
1	0	1	0	A2	A1	A0	note 1

Note

1. This is the read/write bit:
   a) When R/$\overline{W}$ = 1, a read operation is selected.
   b) When R/$\overline{W}$ = 0, a write operation is selected.

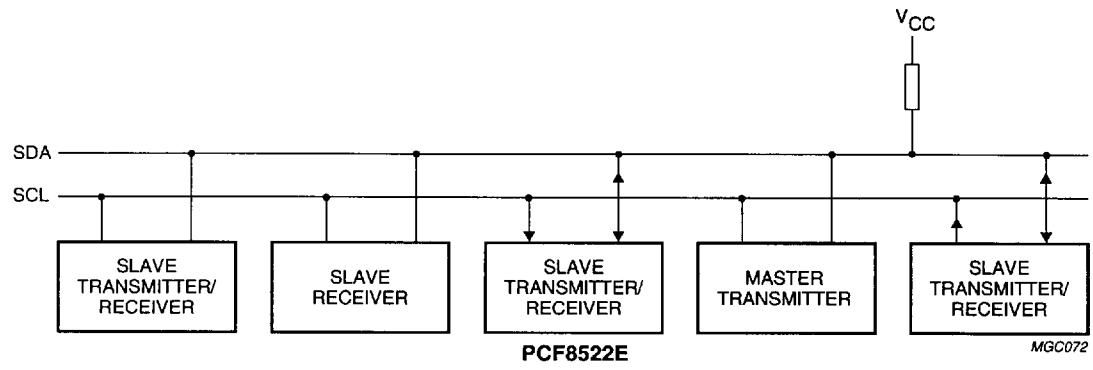


Fig.3 System configuration.

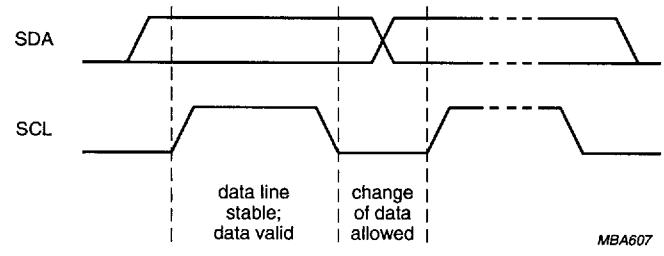


Fig.4 Input data protocol.

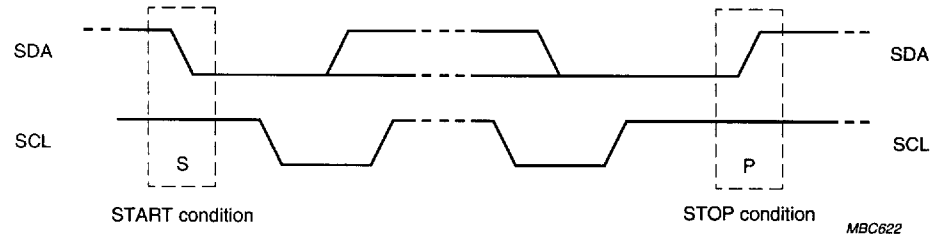


Fig.5 Definition of START and STOP conditions.

7.5 Write operations

The PCF8522E allows two types of write operations:

- Byte write operation; this operation writes a single byte during the nonvolatile write period (t_{WR}).
- Page write operation; this operation allows up to 4-bytes in the same page to be stored during t_{WR}.

7.5.1 BYTE WRITE

For a write operation, the PCF8522E requires a word address field after the slave address. This address field, comprised of 8 bits, with the Most Significant Bit (MSB) 'don't care', provides access to any one of the 256 words of memory.

Upon receipt of the word address, the PCF8522E responds with an acknowledge, and waits for the next 8 bits of data, again responding with an acknowledge. The master then terminates the transfer by generating a STOP condition, at which time the PCF8522E begins the internal write cycle to the nonvolatile array.

While the internal write cycle is in progress, the PCF8522E inputs are disabled, and the device will not respond to any requests from the master. Figure 7 shows an overview of the address, acknowledge and data transfer sequence.

7.5.2 PAGE WRITE

The PCF8522E has the capability to perform a 4 byte page write operation. It is initiated in the same way as the byte write operation, but instead of terminating the write cycle after the first data word is transferred, the master can transmit up to three more words. After the receipt of each word, the PCF8522E will respond with an acknowledge.

The device automatically increments the address for subsequent data words. After the receipt of each word, the two low order address bits are internally incremented by one. The high order 5 bits of the address remain constant. If the master should transmit more than 4 words, prior to generating the STOP condition, the address counter will 'roll over', and the previously written data will be overwritten. In the same way as during a byte write operation, all inputs are disabled during the internal write cycle. Figure 7 shows an overview of the address, acknowledge and data transfer sequence.

7.5.3 ACKNOWLEDGE POLLING

When the PCF8522E is performing an internal write operation, it will not recognize a START condition. Since the device will only return an acknowledge after it accepts the START condition, the part can be continuously queried until an acknowledge is issued, indicating that the internal write cycle is complete.

To poll the device, give it a START condition, followed by a slave address for a write operation (see Fig.8).

7.6 Read operations

Read operations are initiated with setting the R/$\overline{W}$ bit of the slave address byte to logic 1. There are four different read operations:

1. Current address byte read.
2. Random address byte read.
3. Current address sequential read.
4. Random address sequential read.

7.6.1 CURRENT ADDRESS BYTE READ

The PCF8522E contains an internal address counter which maintains the address of the last word accessed, incremented by one. If the last address accessed (either a read or a write operation) was to address location n, the next read operation would access data from address n + 1, and update the current address pointer. When the PCF8522E receives the slave address field with the R/$\overline{W}$ bit set to logic 1, it issues an acknowledge signal and transmits the 8-bit word stored at address n + 1.

The current address read operation only accesses a single byte of data. The master does not acknowledge the transfer, but does generate a STOP condition. At this point, the PCF8522E discontinues the transmission (see Fig.9 for the address, acknowledge and data transfer sequence).

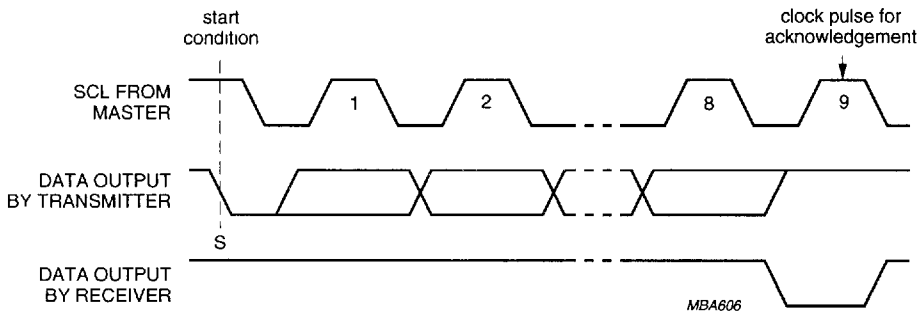


Fig.6 Acknowledge signal on the I²C-bus.

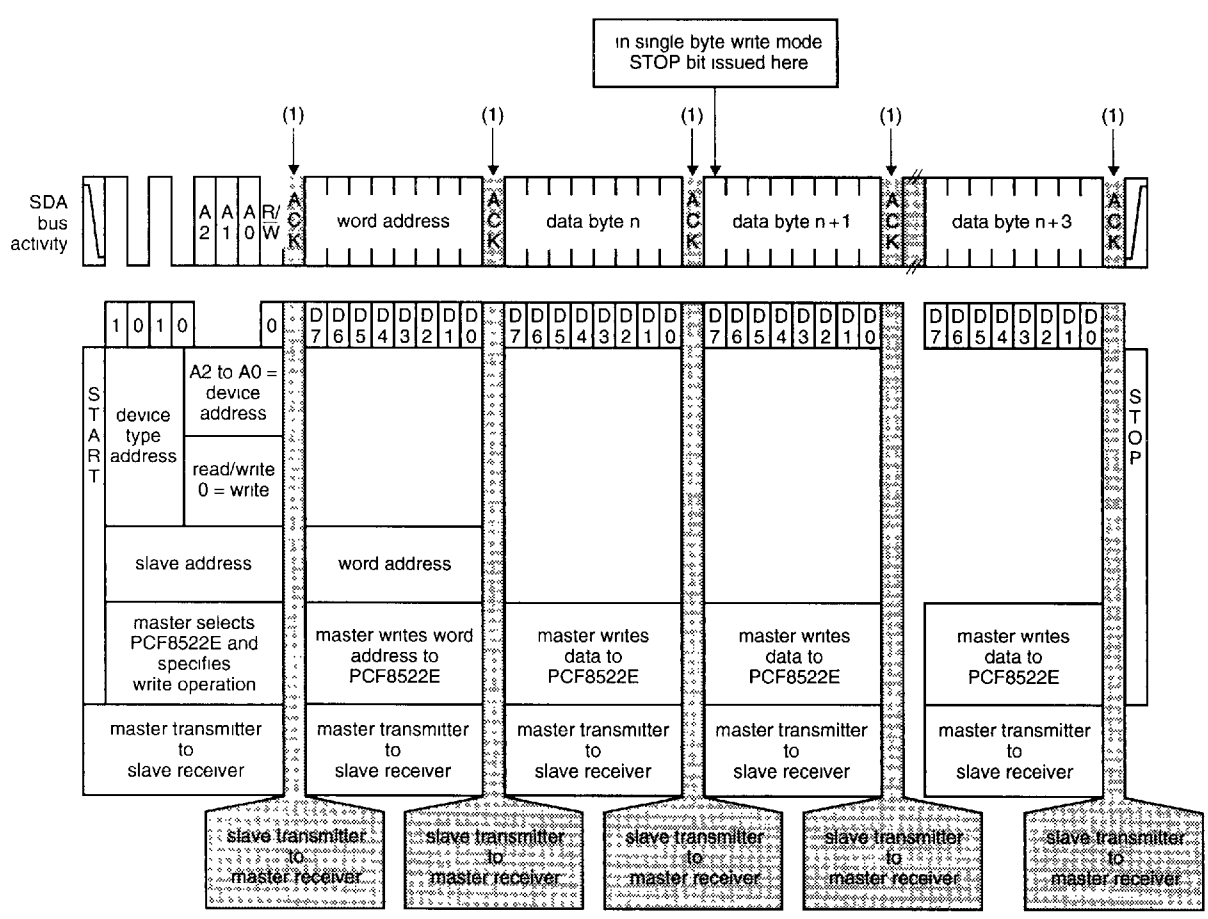


Fig.7 Byte write and page write; address, acknowledge and data transfer sequence.

7.6.2 RANDOM ADDRESS BYTE READ

Random address read operations allow the master to access any memory location at random. This operation involves a two-step process. First the master issues a write command which includes the START condition and the slave address field (with the R/$\overline{W}$ bit set to write), followed by the address of the word it is to read. This procedure sets the internal address counter of the PCF8522E to the desired address.

After the word address acknowledge is received by the master, the master immediately reissues a START condition followed by another slave address field with the R/$\overline{W}$ bit set to read. The PCF8522E will respond with an acknowledge and transmits the 8 data bits stored in the addressed location. At this point, the master does not acknowledge the transmission, but generates the STOP condition. The PCF8522E discontinues the data transmission and reverts to its standby power mode (see Fig.10 for the address, acknowledge and data transfer sequence).

7.6.3 SEQUENTIAL READ

Sequential reads can be initiated as either a current address read or random address read. The first word is transmitted in the same way as during the other byte read modes (current address byte read or random address byte read), but in this event the master responds with an acknowledge signal, indicating that it requires additional data from the PCF8522E.

The PCF8522E continues to output data for each received acknowledge signal. The master terminates the sequential read operation by not responding with an acknowledge signal, and issues a STOP condition.

During a sequential read operation, the internal address counter is automatically incremented with each acknowledge signal. For read operations, all address bits are incremented, allowing the entire array to be read using a single read command.

When the counter reaches the top of the array, it will 'roll over' to the bottom of the array and continue to transmit data for each acknowledge bit it receives (see Fig.11).

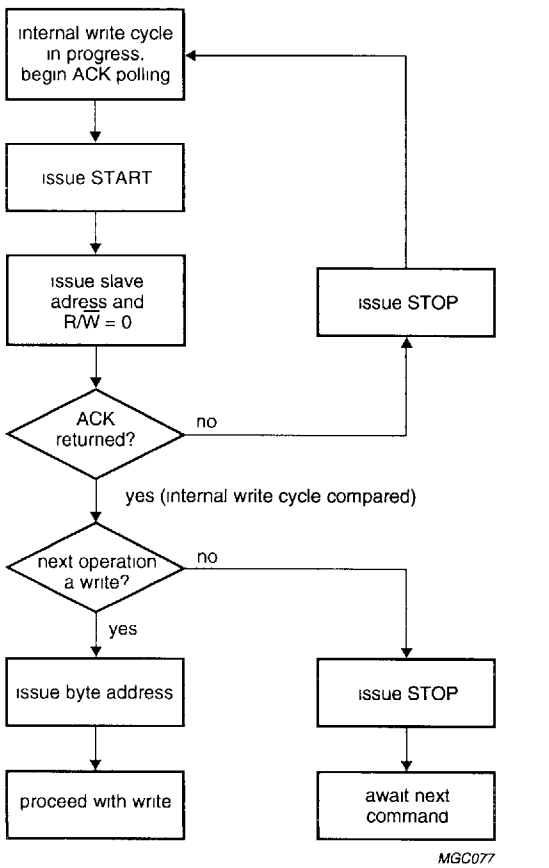


Fig.8 Acknowledge polling.

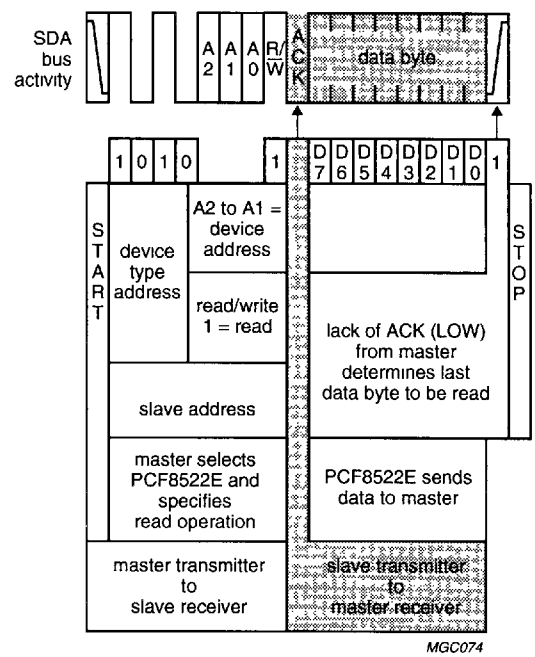


Fig.9 Current address byte read; address, acknowledge and data transfer sequence.

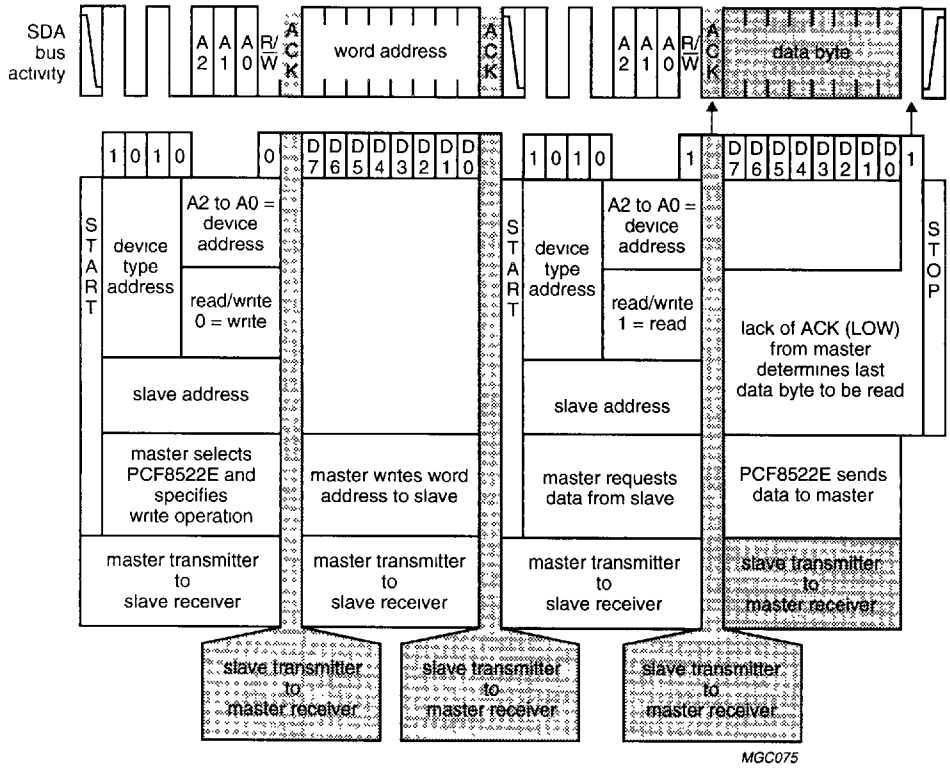


Fig.10 Random address byte read; address, acknowledge and data transfer sequence.

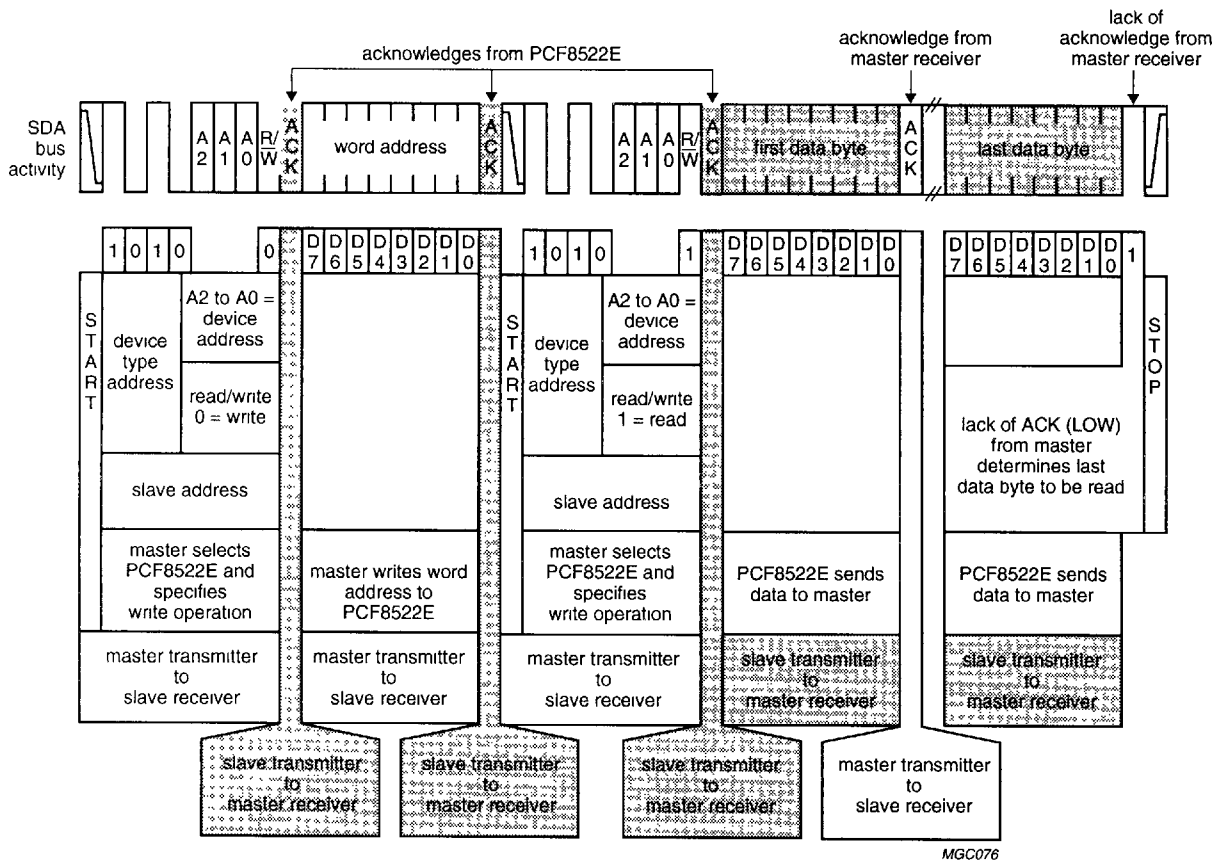


Fig.11 Sequential byte read; address, acknowledge and data transfer sequence.

8 LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage		0	6.5	V
V_n	voltage on any pin		−0.5	V_{CC} + 0.5	V
I_O	output current		−	5	mA
T_{sol}	soldering temperature	<10 s	−	300	°C
T_{stg}	storage temperature		−65	+125	°C
T_{amb}	operating ambient temperature		−40	+85	°C
V_{es}	electrostatic handling	JEDEC method	−2000	+2000	V

9 DC CHARACTERISTICS

V_{CC} = 2.7 to 5.5 V; T_{amb} = −40 to +85 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CC}	supply current (CMOS)	V_{CC} = 5 V ±10%; note 1	−	2	mA
		V_{CC} = 3 V ±10%; note 1	−	1	mA
I_{stb}	standby current (CMOS)	SCL = SDA = V_{CC}; note 2	−	2	µA
I_{LI}	input leakage current	V_I = 0 to V_{CC}	−	10	µA
I_{LO}	output leakage current	V_O = 0 to V_{CC}	−	10	µA
V_{IL}	LOW level input voltage pins A0 to A2, SCL and SDA		−	0.3V_{CC}	V
V_{IH}	HIGH level input voltage pins A0 to A2, SCL and SDA		0.7V_{CC}	−	V
V_{OL}	LOW level output voltage	I_{OL} = 3 mA	−	0.4	V
C_I	input capacitance	T_{amb} = 25 °C; f_{SCL} = 100 kHz	−	5	pF
C_O	output capacitance	T_{amb} = 25 °C; f_{SCL} = 100 kHz	−	8	pF

Notes

1. f_{SCL} = 100 kHz; SDA = open-circuit; all other inputs connected to ground (V_{SS}) or V_{CC}.
2. All other inputs connected to ground (V_{SS}) or V_{CC}.

10 AC CHARACTERISTICS

V_{CC} = 2.7 to 5.5 V; T_{amb} = −40 to +85 °C; unless otherwise specified (see Fig.12); note 1.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
f_{SCL}	SCL clock frequency		0	100	kHz
t_{LOW}	SCL LOW time		4.7	–	µs
t_{HIGH}	SCL HIGH time		4.0	–	µs
t_{BUF}	bus free time	before new transmission	4.7	–	µs
$t_{SU;STA}$	START condition set-up time		4.7	–	µs
$t_{HD;STA}$	START condition hold time		4.0	–	µs
$t_{SU;STO}$	STOP condition set-up time		4.7	–	µs
$t_{VD;DAT}$	SCL LOW-to-SDA data out valid		0.3	3.5	µs
$t_{HD;DAT}$	data hold time	SCL LOW to SDA output data change	0.3	–	µs
t_r	SCL and SDA rise time		–	1000	ns
t_f	SCL and SDA fall time		–	300	ns
$t_{SU;DAT}$	input data set-up time		250	–	ns
$t_{HD;DAT}$	data hold time		0	–	ns
t_{SP}	noise spike width		–	100	ns
$T_{cy(w)}$	write cycle time[2]	V_{CC} = 5 V ±10%	–	10	ms
		V_{CC} = 3 V ±10%	–	25	ms

Notes

1. A detailed description of the I²C-bus specification, with applications, is given in brochure *"The I²C-bus and how to use it"*. This brochure may be ordered using the code 9398 393 40011.
2. Typical $T_{cy(w)}$ = 6 ms if V_{CC} = 5 V ±10%; $T_{cy(w)}$ = 12 ms when V_{CC} = 3 V ±10%.

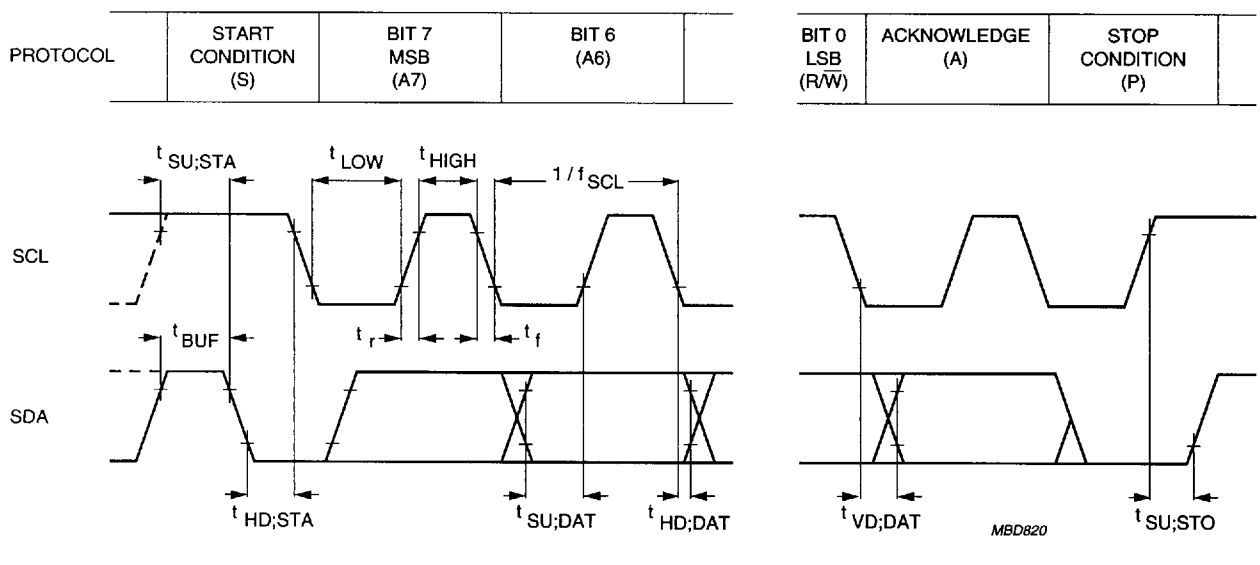
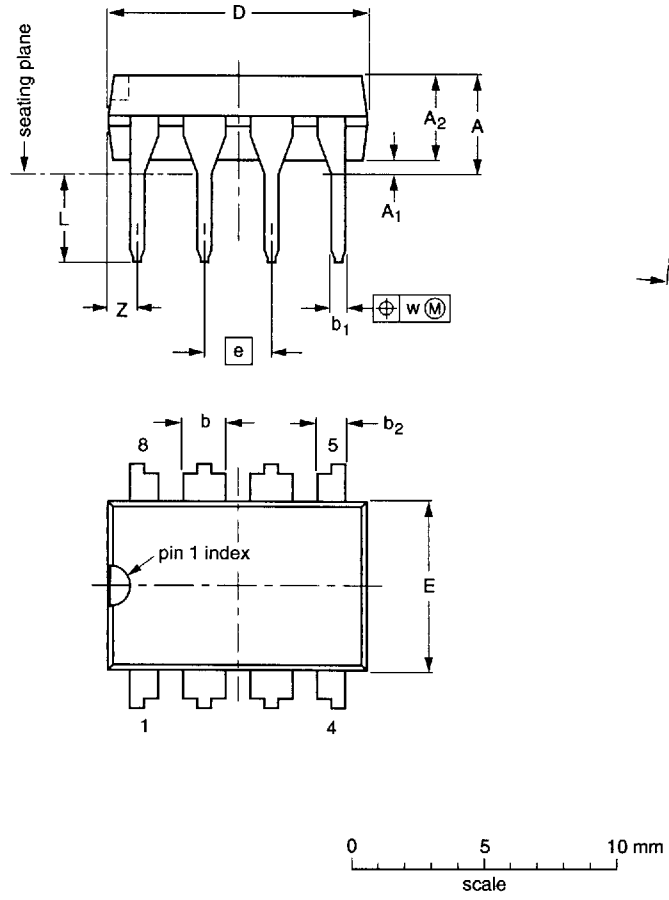


Fig.12 I²C-bus timing diagram.

11 PACKAGE OUTLINES

DIP8: plastic dual in-line package; 8 leads (300 mil) **SOT97-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

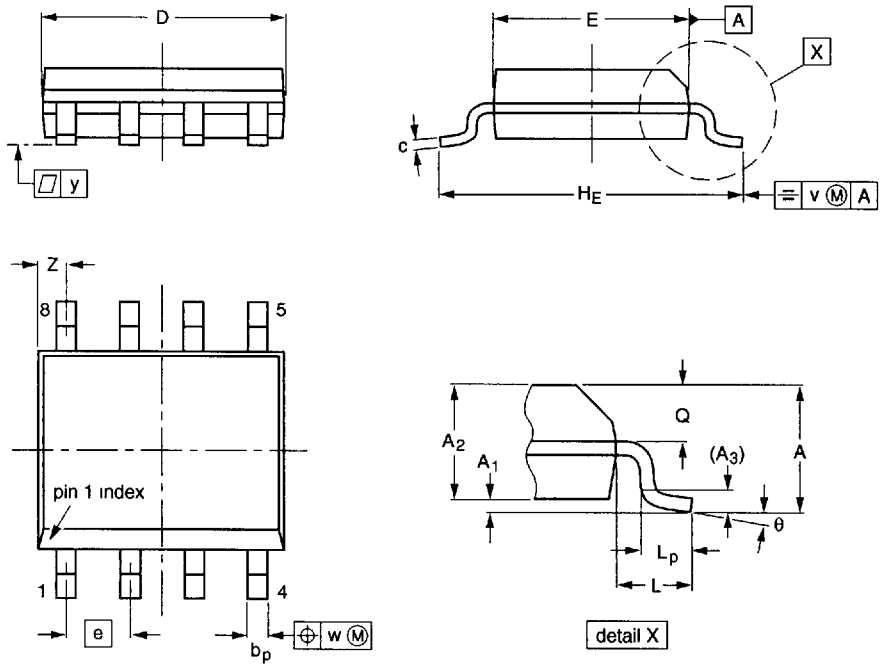
UNIT	A max.	A_1 min.	A_2 max.	b	b_1	b_2	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.14	0.53 0.38	1.07 0.89	0.36 0.23	9.8 9.2	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	1.15
inches	0.17	0.020	0.13	0.068 0.045	0.021 0.015	0.042 0.035	0.014 0.009	0.39 0.36	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.045

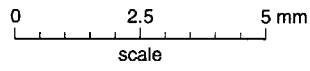
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT97-1	050G01	MO-001AN				~~92-11-17~~ 95-02-04

SO8: plastic small outline package; 8 leads; body width 3.9 mm **SOT96-1**





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.0098 0.0039	0.057 0.049	0.01	0.019 0.014	0.0098 0.0075	0.20 0.19	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT96-1	076E03S	MS-012AA				~~92-11-17~~ 95-02-04

12 SOLDERING

12.1 Plastic dual in-line packages

12.1.1 BY DIP OR WAVE

The maximum permissible temperature of the solder is 260 °C; this temperature must not be in contact with the joint for more than 5 s. The total contact time of successive solder waves must not exceed 5 s.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified storage maximum. If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

12.1.2 REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron below the seating plane (or not more than 2 mm above it). If its temperature is below 300 °C, it must not be in contact for more than 10 s; if between 300 and 400 °C, for not more than 5 s.

12.2 Plastic small outline packages

12.2.1 BY WAVE

During placement and before soldering, the component must be fixed with a droplet of adhesive. After curing the adhesive, the component can be soldered. The adhesive can be applied by screen printing, pin transfer or syringe dispensing.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder bath is 10 s, if allowed to cool to less than 150 °C within 6 s. Typical dwell time is 4 s at 250 °C.

A modified wave soldering technique is recommended using two solder waves (dual-wave), in which a turbulent wave with high upward pressure is followed by a smooth laminar wave. Using a mildly-activated flux eliminates the need for removal of corrosive residues in most applications.

12.2.2 BY SOLDER PASTE REFLOW

Reflow soldering requires the solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the substrate by screen printing, stencilling or pressure-syringe dispensing before device placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt, infrared, and vapour-phase reflow. Dwell times vary between 50 and 300 s according to method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 min at 45 °C.

12.2.3 REPAIRING SOLDERED JOINTS (BY HAND-HELD SOLDERING IRON OR PULSE-HEATED SOLDER TOOL)

Fix the component by first soldering two, diagonally opposite, end pins. Apply the heating tool to the flat part of the pin only. Contact time must be limited to 10 s at up to 300 °C. When using proper tools, all other pins can be soldered in one operation within 2 to 5 s at between 270 and 320 °C. (Pulse-heated soldering is not recommended for SO packages.)

For pulse-heated solder tool (resistance) soldering of VSO packages, solder is applied to the substrate by dipping or by an extra thick tin/lead plating before package placement.